MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	60	V
Average Rectified Forward Current	I _{F(AV)}	3.0 @ T _L = 137°C 4.0 @ T _L = 127°C	А
Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I _{FSM}	125	А
Storage Temperature Range	T _{stg}	- 65 to +175	°C
Operating Junction Temperature (Note 1)	T _J	- 65 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 2) SMC Package SMB Package	$R_{ hetaJL}$	11 15	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2) SMC Package SMB Package	R_{\thetaJA}	136 145	°C/W
Thermal Resistance, Junction-to-Ambient (Note 3) SMC Package SMB Package (Note 4)	$R_{\theta JA}$	71 73	°C/W

ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage (Note 5) (i _F = $3.0 \text{ A}, \text{ T}_{\text{J}} = 25^{\circ}\text{C}$)	V _F	0.63	V
Maximum Instantaneous Reverse Current (Note 5) (Rated dc Voltage, $T_J = 25^{\circ}C$) (Rated dc Voltage, $T_J = 100^{\circ}C$)	İR	0.03 3.0	mA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Mounted with minimum recommended pad size, PC Board FR4.

- 3. 1 inch square pad size (1 x 0.5 inch for each lead) on FR4 board.
- 4. Typical Value; 1 inch square pad size (1 x 0.5 inch for each lead) on FR4 board.
- 5. Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%.

^{1.} The heat generated must be less than the thermal conductivity from Junction-to-Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

TYPICAL ELECTRICAL CHARACTERISTICS

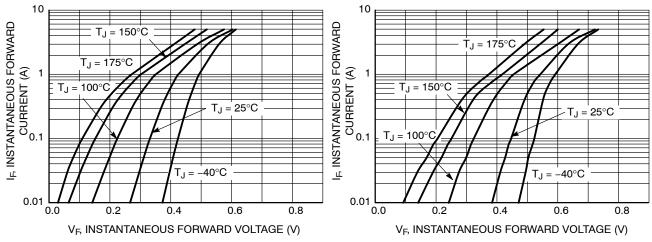
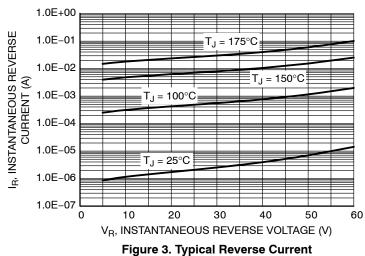


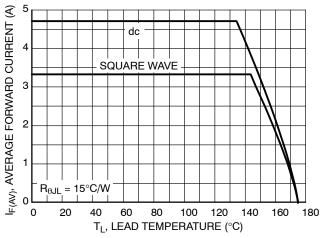
Figure 1. Typical Forward Voltage

Figure 2. Maximum Forward Voltage



1.0E+00 IR, INSTANTANEOUS REVERSE 1.0E-01 $T_J = 175^{\circ}C$ $T_J = 150^{\circ}C$ 1.0E-02 CURRENT (A) T_J = 100°C 1.0E-03 1.0E-04 T_J = 25°C 1.0E-05 1.0E-06 20 30 40 V_R, INSTANTANEOUS REVERSE VOLTAGE (V)

Figure 4. Maximum Reverse Current



P_{FO}, AVERAGE POWER DISSIPATION (W) $T_J = 175^{\circ}C$ SQUARE 3.5 WAVE 3 dc 2.5 1.5 0.5 0 0.5 2 2.5 3 3.5 IO, AVERAGE FORWARD CURRENT (A)

Figure 5. Current Derating

Figure 6. Forward Power Dissipation

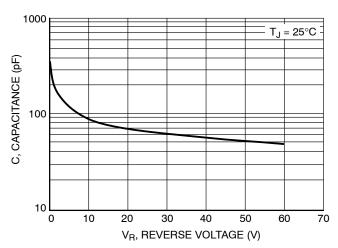


Figure 7. Typical Capacitance

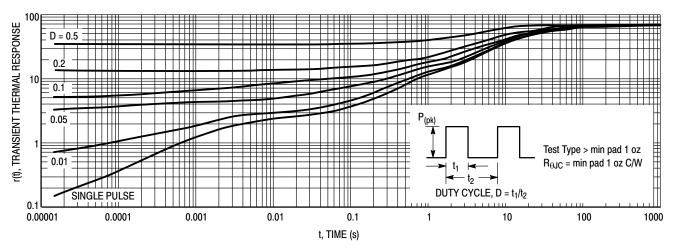


Figure 8. Thermal Response, Junction-to-Ambient, SMC Package

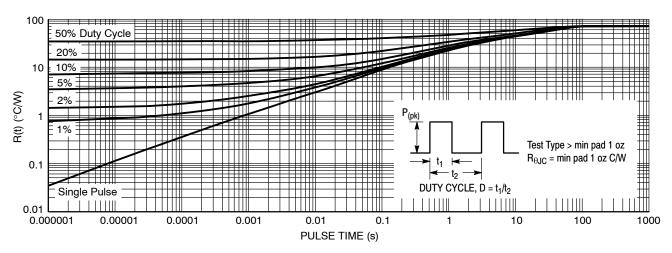


Figure 9. Typical Thermal Response, Junction-to-Ambient, SMB Package

MECHANICAL CASE OUTLINE



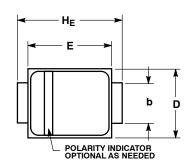


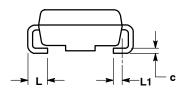
SMB CASE 403A-03 **ISSUE J**

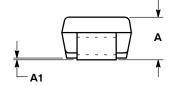
DATE 19 JUL 2012

SCALE 1:1 **Polarity Band**

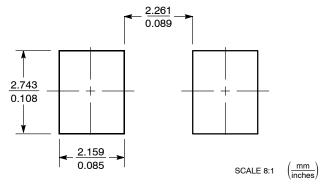
Non-Polarity Band







SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCL.
- 3. DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L1.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	MOM	MAX
Α	1.95	2.30	2.47	0.077	0.091	0.097
A1	0.05	0.10	0.20	0.002	0.004	0.008
b	1.96	2.03	2.20	0.077	0.080	0.087
С	0.15	0.23	0.31	0.006	0.009	0.012
D	3.30	3.56	3.95	0.130	0.140	0.156
E	4.06	4.32	4.60	0.160	0.170	0.181
HE	5.21	5.44	5.60	0.205	0.214	0.220
L	0.76	1.02	1.60	0.030	0.040	0.063
L1	0.51 REF			0.020 REF		

GENERIC MARKING DIAGRAM*





Polarity Band

Non-Polarity Band

XXXXX = Specific Device Code = Assembly Location Α

Υ = Year WW = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

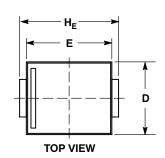
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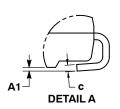
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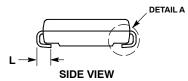


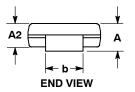
SMC 2-LEAD CASE 403AC **ISSUE B**

DATE 27 JUL 2017

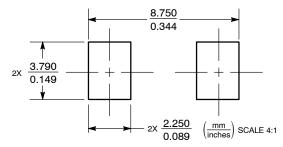








RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

- OTES:

 1. DIMENSIONING AND TOLERANCING PER ANME Y14.5M, 1994.

 2. CONTROLLING DIMENSION: INCHES.

 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.254mm PER SIDE.

 4. DIMENSIONS D AND E TO BE DETERMINED AT DATUM H.

 5. DIMENSION D SHALL BE MEASURED WITHIN THE AREA
- DETERMINED BY DIMENSION L.

	MILLIMETERS		INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	1.95	2.61	0.077	0.103	
A1	0.05	0.20	0.002	0.008	
A2	1.90	2.41	0.075	0.095	
b	2.90	3.20	0.114	0.126	
С	0.15	0.41	0.006	0.016	
D	5.55	6.25	0.219	0.246	
E	6.60	7.15	0.260	0.281	
HE	7.75	8.15	0.305	0.321	
L	0.75	1.60	0.030	0.063	

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code = Assembly Location Α

= Year

WW = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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